



Material Content Data Sheet



Sales Product Name		TLE42794E		Issued		24. January 2018		
MA#		MA001790334						
Package		PG-SSOP-14-2		Weight*		83.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.391	2.87	2.87	28689	28689
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8268	
wire	non noble metal	copper	7440-50-8	27.978	33.57	34.45	335701	344485
	noble metal	gold	7440-57-5	0.157	0.19	0.19	1887	1887
encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1176	
	plastics	epoxy resin	-	4.508	5.41		54089	
	inorganic material	silicondioxide	60676-86-0	44.392	53.26	58.79	532659	587924
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11712	11712
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9210	9210
glue	plastics	epoxy resin	-	0.335	0.40		4023	
	noble metal	silver	7440-22-4	1.006	1.21	1.61	12070	16093
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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